

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JIAN-SHIOU HUANG	08/01/2014
YAO-WEN CHANG	08/01/2014
HSING-LIEN LIN	08/01/2014
CHENG-YUAN TSAI	08/01/2014
CHIA-SHIUNG TSAI	08/01/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14457170
CORRESPONDENCE DATA	
Fax Number:	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	216-502-0600
Email:	docketing@eschweilerlaw.com
Correspondent Name:	ESCHWEILER & ASSOCIATES, LLC.
Address Line 1:	629 EUCLID AVENUE, SUITE 1000
Address Line 2:	NATIONAL CITY BANK BUILDING
Address Line 4:	CLEVELAND, OHIO 44114
ATTORNEY DOCKET NUMBER:	TSMCP470US
NAME OF SUBMITTER:	JAMES R. POTASHNIK
SIGNATURE:	/James R. Potashnik/
DATE SIGNED:	08/12/2014
Total Attachments: 7	

PATENT

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U.S. Patent Appln. No.

Docket No. TSMCP470US

Filing Date

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Jian-Shiou Huang
No.137, Dazhuang Rd.
Fangliao Township, Pingtung County
940, Taiwan (R.O.C.)

Assignor(s):

Yao-Wen Chang
4F-1, No. 15-1, Da Zhi Street
Taipei
104 Taiwan (R.O.C)

Assignor(s):

Hsing-Lien Lin
No.11, Jinshan 16th Street
Jinshan , Hsin-Chu
Taiwan (R.O.C.)

Assignor(s):

Cheng-Yuan Tsai
101, Wen-Yi St
Chu-Pei City, Hsin-Chu county
Taiwan (R.O.C.)

Assignor(s):

Chia-Shiung Tsai
No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road
Hsin-Chu
Taiwan (R.O.C.)

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

“MEMORY STRUCTURE HAVING TOP ELECTRODE WITH PROTRUSION” for which:

a non-provisional application for United States Letters Patent: **PATENT**

REEL: 033512 FRAME: 0647

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Docket No. TSMCP470US

Filing Date

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors.

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and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

✓ 2014/08/01
Date

✓ Jian-Shiou Huang
Name 1st Inventor Jian-Shiou Huang

TSMC Docket No. TSMC2014-0545

U.S. Patent Appln. No.

Docket No. TSMCP470US

Filing Date

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Date

✓ Tao-Wen Chang
Name 2nd Inventor Yao-Wen Chang

TSMC Docket No. TSMC2014-0545

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Docket No. TSMCP470US

Filing Date

✓ 2014/08/01
Date

✓ Hsing-Lien, Lin
Name 3rd Inventor Hsing-Lien Lin

TSMC Docket No. TSMC2014-0545

Docket No. TSMCP470US

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Filing Date

✓ 2014/08/01
Date

✓ Cheng-Yuan Tsai
Name 4th Inventor Cheng-Yuan Tsai

TSMC Docket No. TSMC2014-0545

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Filing Date

✓ 8/1/2014
Date

✓ Chia-Shiung Tsai
Name 5th Inventor Chia-Shiung Tsai